

DERWENT- 2002-126100
ACC-NO:

DERWENT- 200305
WEEK:

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TITLE: Thermosensitive negative board for lithography, has aluminum support body with anodic oxide film, which is subjected to pore widening and sealing processes

PATENT-ASSIGNEE: FUJI PHOTO FILM CO LTD[FUJF]

PRIORITY-DATA: 2000JP-0112285 (April 13, 2000)

PATENT-FAMILY:

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JP 2001293970	A October 23, 2001	N/A	016	B41N 001/14

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APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP2001293970A	N/A	2000JP-0112285	April 13, 2000

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(IPC): G03F007/11

ABSTRACTED-PUB-NO: JP2001293970A

BASIC-ABSTRACT:

NOVELTY - The thermosensitive negative board comprises an ink receiving layer and a hydrophilic layer, formed on an aluminum support body. The aluminum support body has 2 g/m² of anodic oxide film. The ink receiving layer and/or hydrophilic layer contains a light and heat conversion agent. The aluminum support body is subjected to pore widening process, and sealing at a rate of 50% or more.

DETAILED DESCRIPTION - The thermosensitive negative board comprises ink receiving layer and hydrophilic layer containing colloidal particle-like oxide or hydroxide of beryllium, magnesium, aluminum, silicon, titanium, boron, germanium, tin, zirconium, iron, vanadium, antimony or transition metal, on aluminum support body. The aluminum support body has 2 g/m2 of anodic oxide film. The ink receiving layer and/or hydrophilic layer contains a light and heat conversion agent. The aluminum support body is subjected to pore widening process, and sealing at a rate of 50% or more.

USE - For lithography.

ADVANTAGE - The sensitivity of thermosensitive negative board is improved. Since aluminum board is used as support body, thermosensitive board is provided in the printer and printed directly without image development process.

CHOSEN- Dwg. 0/0
DRAWING:

TITLE- THERMOSENSITIVE NEGATIVE BOARD LITHO ALUMINIUM SUPPORT
TERMS: BODY ANODE OXIDE FILM SUBJECT PORE WIDE SEAL PROCESS

DERWENT-CLASS: G07 P75 P84 S06

CPI-CODES: G05-A01; G06-B03; G06-D05;

EPI-CODES: S06-A01X;

UNLINKED-DERWENT- ; 1498U ; 1500U ; 1507U ; 1507U ; 1508U ; 1509U ;
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